

MIL-SPEC Certified Ruggedized Edge Platform

Ruggedized Edge Compute Platform for Extreme Conditions



Key Features

- Ideal for processing Edge Al workloads, latency sensitive IoT applications
- > Mobile Edge Computing and 5G at the edge
- > 2U, 19" MIL-SPEC optimized chassis with ruggedized enclosure
- Compliant with MIL-STD-810 for temperature, humidity, shock & vibration, and MIL-STD-461 for EMI/EMC
- Customizable and optimized with 56 CPU cores and 1024GB of DDR5
- 3 NVIDIA® L4 Tensor Core GPUs and 1S Intel® Xeon® 6 CPU

Specifications

Dimensions	2U (W434.4 x H88.1 x D472mm) Server (W605 x H97.8 x D605 mm) Case	PCIe Expansion	3x PCIe x16 PCIe Gen5 GPU Slot 1x PCIe x16 PCIe Gen5 NIC Slot
Motherboard	Hyve-designed MB HS9120	I/O Ports	Rear Side: 1x Power Button/Power LED 1x Reset Button 1x System healthy LED 2x USB 3.0 Compliant Type A 1x Mini DP
Weight	32.5 lbs (14.7 Kg) without rugged case 85.2 lbs (38.6 Kg) with rugged case combined weight		
CPU	Intel® Xeon® 6		
Socket	1S		1x RJ45 Management LAN
Chipset	System on Chip	Backplane	N/A
Chipset Memory	System on Chip 8x RDIMM 4800MT/s DDR51 DPC	Backplane TPM	N/A TPM2.0 SLB 9670
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Memory	8x RDIMM 4800MT/s DDR5 1 DPC 1x 1G R45 for management 2x M.2 PCle Gen4 x2 (Boot)	TPM	TPM2.0 SLB 9670
Memory LAN Storage	8x RDIMM 4800MT/s DDR5 1 DPC 1x 1G R45 for management 2x M.2 PCle Gen4 x2 (Boot) 4x U.2 PCleGen5 x4 (Data)	TPM Power Supply	TPM2.0 SLB 9670 1x CRPS PSU, 1300W
Memory LAN	8x RDIMM 4800MT/s DDR5 1 DPC 1x 1G R45 for management 2x M.2 PCle Gen4 x2 (Boot)	TPM Power Supply System Management	TPM2.0 SLB 9670 1x CRPS PSU, 1300W DC-MHS Aspeed AST2600

